SPECIFICATION

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SPEC. NO.: PS-50299-XXXXX-XXX **REVISION:** J

PRODUCT NAME: 2.0 MM WTB HEADER CONN

T/H R/A TYPE

PRODUCT NO: 50298 SERIES 50299 SERIES; 50300 SERIES; 50302 SERIES; 50411 SERIES; 51298 SERIES;51277SERIES

PREPARED:	CHECKED:	APPROVED:
SHI,YANAN	**BRAVE**	**BRAVE**
DATE: **2019-11-29**	DATE: **2019-11-29**	DATE: **2019-11-29**

1. Revision History

Rev.	ECN #	Revision Description	Prepared	Date
O	ECN-0812248	NEW SPEC	JASON	2008.12.5
A	ECN-1003105	ADD 50411 SERIES；	JASON	2010.03.15
B	ECN-1005146	MODIFY CURRENT RATING	JASON	2010.05.20
C	ECN-1302073	ADD 51298 SERIES	CHENBO	2013.1.19
D	ECN-1401172	ADD WORKNG VOLTAGE	XUFEI	2014.01.09
E	ECN-1405203	ADD THERMAL SHOCK AND HAND SOLDERING	TANGENHUI	2014.05.13
F	ECN-1501167	ADD 51277 SERIES	XIUJIN	2015.01.16
G	ECN-1501327	ADD AWG#24	JUGG	2015.1.28
H	ECN-1605020	ADD L LC R INITIAL VALUES	XIUJIN	2016.04.15
J	ECN-1912182	Update UL10064 AWG#24 Current	SHI,YANAN	2019.11.29

2.SCOPE

This specification covers performance, tests and quality requirements for 2.0mm pitch wire to board connector. Including these product series as belows ： 50298 series, 50299 series.50300 series. 50302 series; 50411 Series;51298 Series.

3.APPLICABLE DOCUMENTS

EIA-364: ELECTRONICS INDUSTRIES ASSOCIATION

4.REQUIREMENTS

4.1 Design and Construction

Product shall be of design, construction and physical dimensions specified on applicable product drawing.

4.2 Materials and Finish

4.2.1 Contact: High performance copper alloy
Finish: Pls see P/N LEGEND
4.2.2 Housing: Thermoplastic or Thermoplastic High Temp., UL94V-0

4.3 Ratings

4.3.1 Working voltage less than 36 volts (per pin)
4.3.2 Voltage: 200 Volts AC (per pin)
4.3.3 Current: AWG#24 DC 4.5 Amperes (per pin)
AWG#26 DC 3 Amperes(per pin)
AWG#28 DC 2.5 Amperes(per pin)
AWG#30 DC 1.5 Amperes(per pin)
4.3.4 Operating Temperature : -40℃ to +85℃

5.Performance

5.1. Test Requirements and Procedures Summary

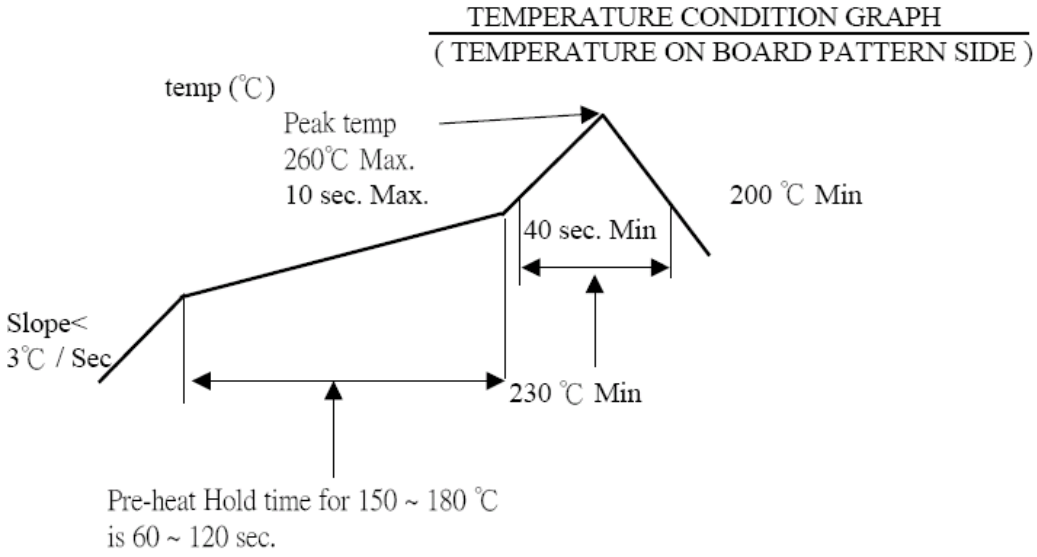
Item	Requirement	Standard
Examination of Product	Product shall meet requirements of applicable product drawing and specification.	Visual, dimensional and functional per applicable quality inspection plan.
ELECTRICAL		
Item	**Requirement**	**Standard**
Low Level Contact Resistance	50 m Ω Max.(initial)per contact 25 m Ω Max. Change allowed	Mate connectors, measure by dry circuit, 20mV Max., 10mA Max. (EIA-364-23)
Insulation Resistance	1000 M Ω Min.	Unmated connectors, apply 500 V DC between adjacent terminals. (EIA-364-21)
Dielectric Withstanding Voltage	No discharge, flashover or breakdown. Current leakage: 1 mA max.	500 VAC Min. at sea level for 1 minute. Test between adjacent contacts of unmated connectors. (EIA-364-20)
Temperature rise	30℃ Max. Change allowed	Mate connector: measure the temperature rise at rated current until temperature t stable. The ambient condition is still air at 25℃ (EIA-364-70 METHOD1,CONDITION 1)
MECHANICAL		
Durability	60 cycles	The sample should be mounted in the tester and fully mated and unmated the number of cycles specified at the rate of 25.4 ± 3mm/min. (EIA-364-09)
Mating / Unmating Forces	Mating Force: See item 8 Unmating Force: See item 8	Operation Speed: 25.4 ± 3 mm/minute.. Measure the force required to mate/Unmate connector. (EIA-364-13)
Contact Retention Force	0.5 Kgf Min.	Operation Speed: 25.4 ± 3 mm/minute. Measure the contact retention force with Tensile strength tester.
Vibration	1 μs Max.	The electrical load condition shall be 100 mA maximum for all contacts. Subject to a simple harmonic motion having amplitude of 0.76mm (1.52mm maximum total excursion) in frequency between the limits of 10 and 55 Hz. The entire frequency range, from 10 to 55 Hz and return to 10 Hz, shall be

		traversed in approximately 1 minute. This motion shall be applied for 2 hours in each of three mutually perpendicular directions. (EIA-364-28 Condition I)
MECHANICAL		
Item	**Requirement**	**Standard**
Shock (Mechanical)	1 μs Max.	Subject mated connectors to 50 G's (peak value) half-sine shock pulses of 11 milliseconds duration. Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks). The electrical load condition shall be 100mA maximum for all contacts. (EIA-364-27, test condition A)
ENVIRONMENTAL		
Resistance to **Reflow** Soldering Heat	See Product Qualification and Test Sequence Group 8 **(Lead Free)**	Pre Heat：150℃~180℃, 60~120sec. Heat:230℃ Min., 40sec Min. Peak Temp:260℃Max, 10sec Max.
Thermal Shock	See Product Qualification and Test Sequence Group 4	Mate module and subject to follow condition for 5 cycles. 1 cycles: -55 +0/-3 ℃, 30 minutes +85 +3/-0 ℃, 30 minutes (EIA-364-32, test condition I)
Humidity-Temperature Cycle	See Product Qualification and Test Sequence Group 4	Mated Connector 40℃, 90~95% RH, 96 hours. (EIA-364-31,Condition A, Method II)
Temperature life	See Product Qualification and Test Sequence Group 5	Subject mated connectors to temperature life at 85℃ for 96 hours. (EIA-364-17, Test condition A)
Salt Spray	See Product Qualification and Test Sequence Group 6	Subject mated/unmated connectors to 5% salt-solution concentration, 35℃ for 8 hours. (EIA-364-26,Test condition B)
Solder ability	Solder able area shall have minimum of 95% solder coverage.	And then into solder bath, Temperature at 245 ±5℃, for 4-5 sec. (EIA-364-52)
Hand Soldering Temperature Resistance	Appearance: No damage	T≧350℃, 3sec at least.

Note. Flowing Mixed Gas shell be conduct by customer request.

6.INFRARED REFLOW CONDITION

6.1. Lead-free Process



7.PRODUCT QUALIFICATION AND TEST SEQUENCE

Test or Examination	Test Group									
	1	2	3	4	5	6	7	8	9	10
	Test Sequence									
Examination of Product				1、7	1、6	1、4			1	1
Low Level Contact Resistance		1、5	1、4	2、10	2、9	2、5			3	
Insulation Resistance				3、9	3、8					
Dielectric Withstanding Voltage				4、8	4、7					
Temperature rise	1									
Mating / Unmating Forces		2、4								
Durability		3								
Contact Retention Force								1		
Vibration			2							
Shock (Mechanical)			3							
Thermal Shock				5						
Humidity				6						
Temperature life					5					
Salt Spray						3				
Solder ability							1			
Resistance to Soldering Heat									2	
Hand Soldering Temperature Resistance										2
Sample Size	2	4	4	4	4	4	2	4	4	4

8.Insertion / Extration Force

Units: kgf

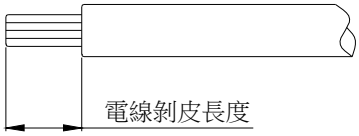
Number of circuits	At initial		At 60th
	I.F.(MAX.)	W.F.(MIN.)	W.F.(MIN.)
2	2.00	0.30	0.20
3	2.00	0.30	0.20
4	2.00	0.30	0.20
5	2.50	0.40	0.30
6	2.50	0.40	0.30
7	3.00	0.50	0.40
8	3.00	0.50	0.40
9	3.50	0.60	0.50
10	3.50	0.60	0.50
11	4.00	0.70	0.60
12	4.00	0.70	0.60

9.APPLICABLE WIRES

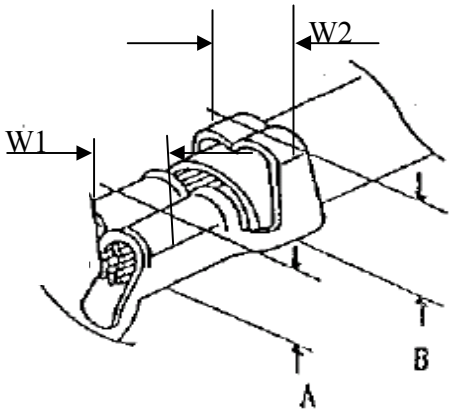
AWG Size:AWG#30~#24
Insulation OD:Φ0.70~0.90mm

10. CRIMPING CONDITION

鉚線條件表 CRIMPING CONDITION							
Part Number	Wire Specification			Crimp Height (mm)		Crimp Width (mm)	
	UL Style	AWG Size	Insulation OD(mm)	Conductor A	Insulation B	Conductor W1	Insulation W2
88301-W	UL1571	26	0.90	0.78~0.83	0.98~1.03	0.90(Ref.)	1.50 max.
	UL1571	28	0.80	0.70~0.75	0.86~0.91	0.80(Ref.)	1.50 max.
	UL1571	30	0.70	0.64~0.69	0.75~0.80	0.70(Ref.)	1.50 max.
	UL10064	24	0.85	0.62~0.67	1.32~1.37	0.85(Ref.)	1.50 max.



Strip length



Note:

1、W1為芯線導體鉚壓後之寬度(Conductor Crimping Width)：W1值如上表

2、W2為電線外被部分鉚壓後之寬度(Insulation Crimping Width)：W2值如上表

3、A為芯線導體鉚壓後之高度(Conductor Crimping height)：A值如上表(參考值）

4、B為電線外被鉚壓後之高度(Insulation Crimping height)：B值如上表(參考值）

5、電線剝皮長度(Strip length)：1.3~1.7mm(參考值)